

Supplementary Materials

Table S1. Elemental composition (wt %) of microchip pieces detached from PCBs after leaching with Fe³⁺.

	Sn	Cu	Ag	Ba	S	Fe	P	Gd	K
Biotic sim- ple	44.73	30.39	8.30	6.49	5.13	2.96	0.79	0.56	0.29
	Si	Mg	Sr	Cl	Al	Na	Ca	Ni	Zn
	0.18	0.12	0.06	bdl	bdl	bdl	bdl	bdl	bdl
Abiotic sample	Ba	Cu	Sn	S	Ag	Fe	Si	Al	Ca
	34.32	19.10	18.06	10.95	5.67	3.65	1.87	1.60	1.15
	P	Gd	Mg	Ni	K	Na	Cl	Sr	Zn
	0.94	0.62	0.56	0.38	0.34	0.34	0.33	0.10	0.04

bdl = below detection limit

Table S2. Elemental composition (wt %) of submillimetreal components detached from PCBs after leaching with Fe³⁺.

	Ni	Ba	Sn	Ti	Fe	Zr	S	Al	Ag
Abiotic sample	31.36	26.53	7.89	7.73	6.36	5.26	3.20	2.70	2.65
	Si	Cl	Sr	Cu	K	Pb			
	1.74	1.30	1.20	1.04	0.76	0.29			

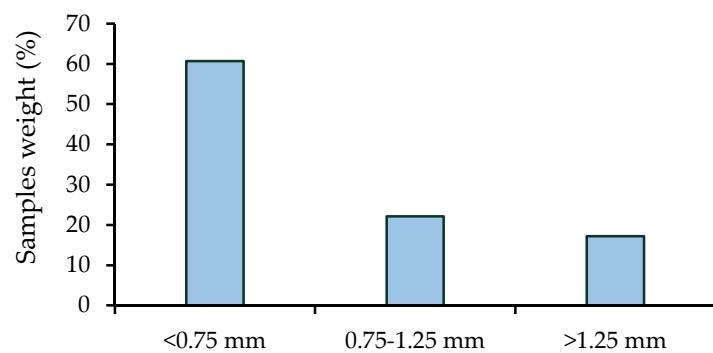


Figure S1. Particle-size distribution of pulverized PCB.

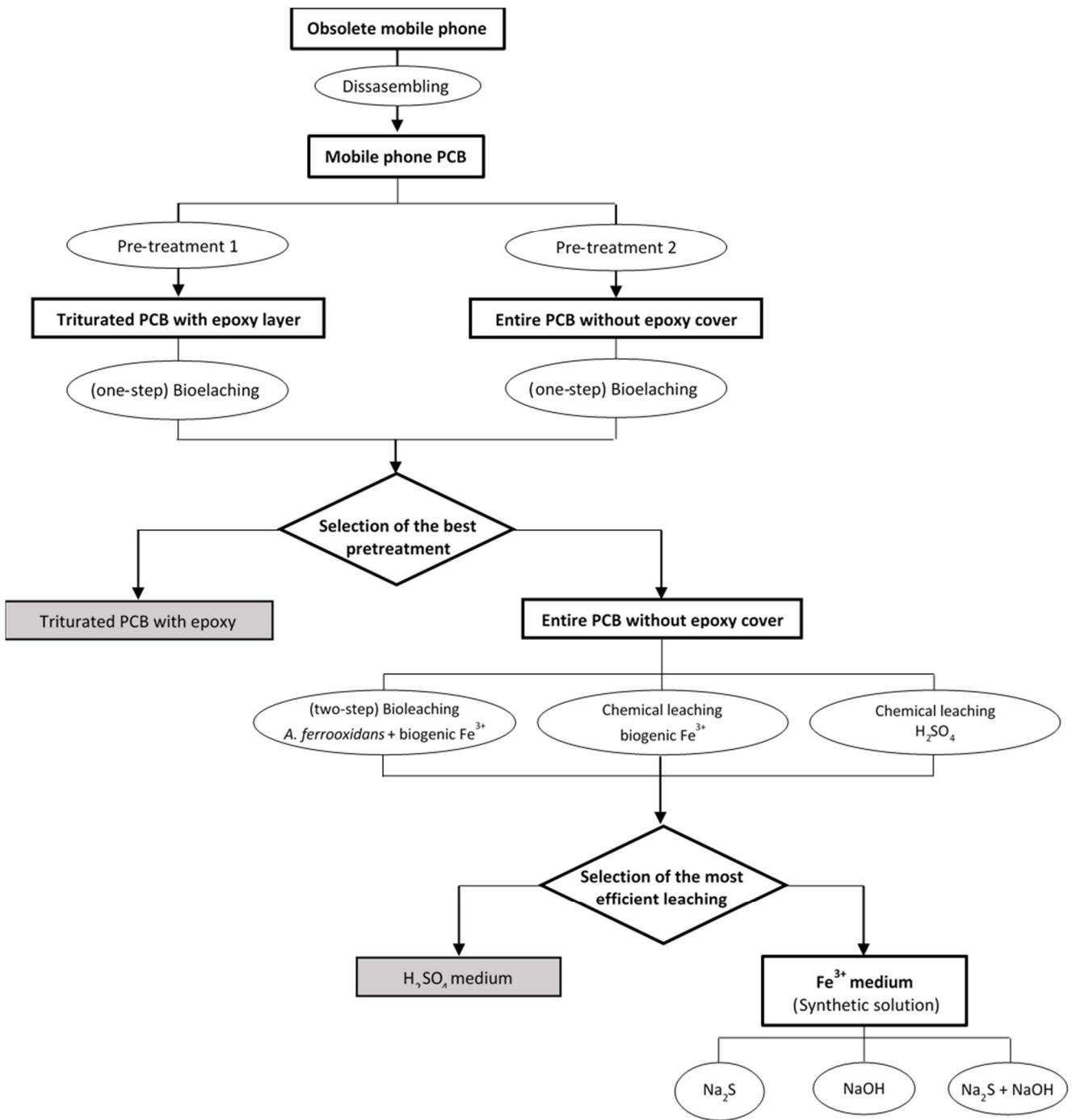


Figure S2. A schematic flowchart illustrating the experimental design.

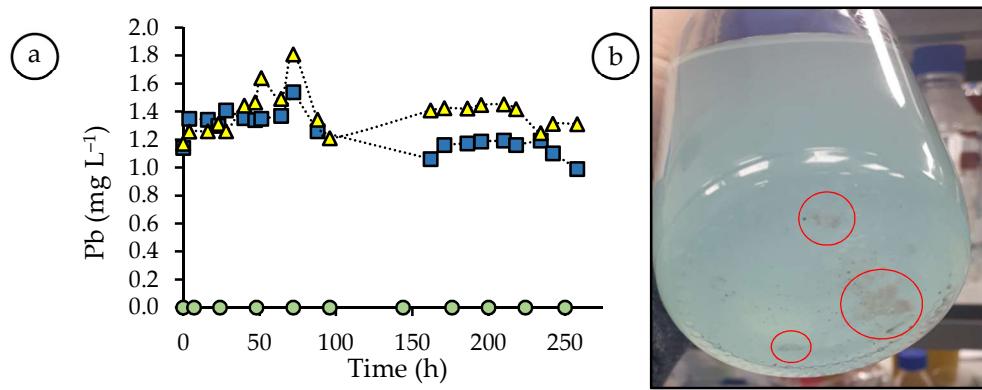


Figure S3. (a) Lead concentration during the two-step bioleaching experiment (blue square) and leaching experiments in abiotic medium, employing biogenic Fe³⁺ (yellow triangle) or H₂SO₄ (green circle) as leaching agents. (b) PbSO₄ precipitate formed in the leaching medium containing H₂SO₄.